MONNAN HOW

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Summary

Familiar with SDLC, OOD/OOP, software testing (white box/structural testing and black box/functional testing), database, data structure and algorithms and statistical modeling. Special interest in machine learning, data science and artificial intelligence related technologies.

Three years of working experience as a process engineer in a fast-pace semiconductor manufacturing company I have developed skills for communication, multi-projects managing and problem-solving.

Technical Skills

Proficient: Python, Excel.

Experience: SQL, Python libraries (pandas, numpy, seaborn, Scikit-learn, matplotlib), Java, C, Hadoop, Hive, R, HTML/CSS/JS, Django, Linux commands (Bash).

Employment History

uPI Semiconductor Corp.

Data Modeling Intern

Milpitas, CA

Aug 2019 – present Write programs to help data processing in intermediate stages (data format changing, handle missing

Taiwan Semiconductor Manufacturing Company (TSMC)

data) to improve engineer's productivity.

Process Engineer

Tainan, Taiwan

Oct 2013 – *Oct* 2016

- Initiated and build a dashboard to monitor bottle neck recipe availability that saved 80% of a Chief Process Engineer time on recipe management.
- Solved a production line quality issue through data analysis and reduce 20% out of control rate.
- Successfully predicted process outcome base on process parameters with 80% accuracy.

Projects

- Artificial Intelligence Pacman game (in-class)
 - Implement DFS, BFS, UCS, A*, MinMax, alpha-beta pruning, Q-Learning (Reinforcement Learning/Machine Learning) algorithms to solve problems in game (Python code).
- **Compiler construction (in-class)**
 - Constructed a C compiler using lexer and parser such as flex, yacc/bison (C code).
- **Billing Interface Linkable Library (in-class)**
 - Build an API to query and update student records database (Java code).
 - Junit for software testing.

Education

University of South Carolina

Master of Science in Computer Science, GPA 3.7

National Cheng Kung University

Master of Science in Material Science and Engineering, GPA 3.8

Columbia, SC *Sep 2017 – May 2019*

Tainan, Taiwan

Sep 2010 – June 2012